

ams invests over €25m to create dedicated in-house production capacity for analog 3D ICs

Soaring demand for stacked-die devices shows value of ams' patented TSV fabrication technology

Unterpremstaetten, Austria (3 September, 2013), ams AG (SIX: AMS), a leading provider of high performance analog ICs and sensor solutions, today announced that it has invested over €25m to create dedicated 3D IC production capacity at its wafer fabrication plant near Graz, Austria.

The investment provides for the installation of new 3D IC equipment in clean room space available at the plant, situated at the company's headquarters.

The additional production capacity comes in response to a surge in demand outlook for ICs fabricated with 3D IC integration technology developed exclusively by ams. The patented technology enables the design and production of radically improved IC packages that are smaller and offer better device performance than existing packages.

For instance, the TSV (Through-Silicon Via) interconnects in 3D ICs from ams can replace the bond wires in conventional single-die devices. For optical semiconductors, clear packaging requirements are eliminated to enable production of chipscale packages that are smaller, cheaper, and less vulnerable to EMI (electro-magnetic interference).

The ams 3D IC process also enables the production of stacked-die devices. Two die produced in different processes (such as a photodiode die and a silicon signal-processing die) are bonded back-to-back to produce a monolithic stacked-die device. This can replace two separate packages, has a far smaller footprint, and features much shorter interconnects, resulting in improved performance and reduced electrical noise.

The new equipment line, which will be fully operational by the end of 2013, will be available for production of 3D ICs for any ams product or full-service foundry customer. Initially the line will produce devices for customers in the medical imaging and mobile phone markets.

Kirk Laney, CEO of ams, commented: "The new 3D IC production line is a substantial investment for a company the size of ams, and it demonstrates once again our commitment to the development and deployment of advanced analog semiconductor fabrication technology. Our customers highly value our ability to implement innovative fabrication techniques, and to offer production capacity with the ultra-high quality that they require."



About ams

ams develops and manufactures high performance analog semiconductors that solve its customers' most challenging problems with innovative solutions. ams' products are aimed at applications which require extreme precision, accuracy, dynamic range, sensitivity, and ultra-low power consumption. ams' product range includes sensors, sensor interfaces, power management ICs and wireless ICs for customers in the consumer, industrial, medical, mobile communications and automotive markets.

With headquarters in Austria, ams employs over 1,300 people globally and serves more than 7,800 customers worldwide. ams is the new name of austriamicrosystems, following the 2011 acquisition of optical sensor company TAOS Inc. ams is listed on the SIX Swiss stock exchange (ticker symbol: AMS). More information about ams can be found at www.ams.com.

for further information

Media Relations

ams AG
Ulrike Anderwald
Director Marketing Communications
T +43 (0) 3136 500 31200
press@ams.com
www.ams.com

Technical Contact

ams AG
Andreas Wild
Marketing Manager, Full Service Foundry
T +43 3136 500 31246
andreas.wild@ams.com
www.ams.com